

300mmSemi-Automatic UV Irradiation System

RAD-2010m/12



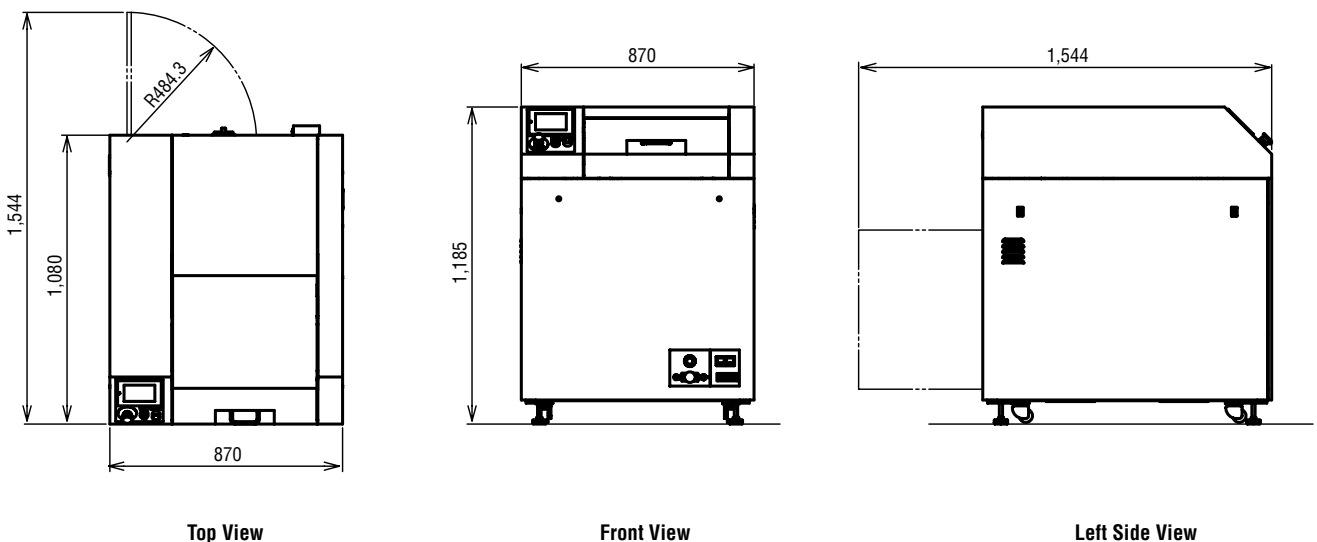
Outline

- A semi-automatic UV irradiation system for UV curable dicing tape attached to ring frame for 300mm wafer.
- The new system offers reduced footprint as well as improved operability and visibility, compared to our conventional 300mm semi-automatic UV irradiation system. Also, double irradiation of ring frame for 150mm is available as an option.

Suitable Tapes

- Dicing tape : Adwill D series
- Dicing die bonding tape : Adwill LE Tape

External View



Facility

Power Supply	Voltage	: AC200-230V ±10% (±AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Capacity	: 4.0kW
	Air pressure	: 0.5-0.8MPa
Nitrogen Source	Air consumption	: >10L/min (ANR)
	Nitrogen pressure	: 0.29-0.31MPa
	Nitrogen consumption	: >30L/min (ANR)

Suitable ring frame size

ring frame for 300mm wafer
* Ring frame for 150mm and 200mm available
* Double irradiation of ring frame for 150mm wafer

Size

Width : 870mm
Depth : 1,080mm
Height : 1,185mm

Weight

About 300kg

Processing Capacity

within 22sec/wafer(excludes setting time)



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